

Laser Ceramic Cutting Machine AP-CC-05I

Introduction:

The equipment adopts a high-precision optical system, equipped with a highly stable working platform. It is used for high-energy laser processing such as marking, drilling, and cutting on ceramic materials like aluminum oxide and aluminum nitride.

Features:

- High-precision optical system, highly stable working platform.
- Non-contact processing, optically maintenance-free.
- Good product consistency, high yield.
- Industrial design, ensuring processing precision and operational stability under 24/7 operation.



Specifications subject to change without notice

Main Specifications:

Parameter	Specification
Laser type	Fiber laser
Processing ceramic thicknesses	≤2 mm / 0.0787 inch
Cutting shape	Linear or irregular
Cutting speed	15 pcs/h @ 10X23 mil (4 inch)
Cutting material	Ceramics like aluminum oxide and aluminum nitride
Power supply	AC 208V 50/60 Hz; total 5 kW (including vacuum and cooling system)
Cooling method	Water cooling
Outer dimensions	1205X1270X1882 (mm) / 3.95 X 4.17 X 6.17 (ft)
Total weight	1.21 (Ton)
Working environment	15 – 30 °C, humidity 20 – 80%

Applications:

Cutting and drilling on ceramics like aluminum oxide and aluminum nitride.

Samples:

